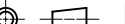


NOTES:

- 適合ハウジング: 501189****
APPLICABLE 501330****
HOUSING 501939****
- めっき仕様: 表題欄参照
PLATING:SEE TABLE
- 本製品はコンタクト部 金めっき品である。
THIS PRODUCT IS GOLD PLATING FOR CONTACT POINT.
- 本製品はバレル外面 錫めっき品である。
THIS PRODUCT IS TIN PLATING OUTSIDE A BARREL.
- 圧着条件については、
圧着仕様書(CS-501193-001)を参照願います。
PLEASE REFER TO CRIMP SPECIFICATION (CS-501193-001).
- 製品の取扱いについては、コネクタ取扱い
説明書(5013300000 PS A00,A01) を参照願います。
PLEASE REFER TO INSTRUCTION MANUAL(5013300000 PS A00,A01).

1.27μm MIN.	0.9μm MIN.	0.76μm MIN.	5011935100	バラ状 LOOSE
			5011935000	連鎖状 CHAIN
		0.38μm MIN.	5011936100	バラ状 LOOSE
			5011936000	連鎖状 CHAIN
1.0μm MIN.		0.1μm MIN.	5011933100	バラ状 LOOSE
			5011933000	連鎖状 CHAIN
下地：ニッケルめっき UNDER PLATING: NICKEL PLATING	バレル外側：錫めっき OUTSIDE OF BARREL: TIN PLATING	接点部：金めっき CONTACT AREA : GOLD PLATING	オーダー番号 ODER NO.	端子形状 FORM
めっき仕様(前めっき) : PLATING(PRE-PLATING)				

MATERIAL りん青銅 下地ニッケル、部分金めっき、錫めっき品 PHOSPHOR BRONZE t=0.12, SELECTIVE GOLD PLATING, SELECTIVE TIN PLATING, UNDER NICKEL PLATING	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: REDRAWN AND REVISED		<div>molex</div> <div>PICO-CLASP 1.0 W/B CONN CRIMP REC TERM (GOLD PLATING)</div>			
	DIMENSION UNITS mm	SCALE 20:1						
FINISH SEE NOTE	GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 122939		PRODUCT CUSTOMER DRAWING			
	ANGULAR TOL ± 3.0 °		DRWN: KYAMADA02 2018/02/14					
WIRE RANGE AWG#28-32	4 PLACES	± 0.2	CHK'D: SAKIYAMA 2018/06/20		DOCUMENT NUMBER 5011930000			
	3 PLACES	± 0.2	APPR:					
INS. RANGE Ø0.4-0.8	2 PLACES	± 0.2	INITIAL REVISION:		MATERIAL NUMBER SEE TABLE			
	1 PLACE	± 0.2	DRWN: QHE31 2017/04/03					
	0 PLACES	± 0.2	APPR: TKANEKO 2017/04/06		SHEET NUMBER 1 OF 1			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION 	DRAWING A3-SIZE				
			SERIES 501193					

DOCUMENT STATUS	RV	RELEASE DATE	
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